Processor AMC based on Intel[®] Next Generation Core™ i (Gladden)

AMC722





KEY FEATURES

- Single-width, mid-height (option for full-height) per AMC.0
- Processor AMC with Intel[®] Next Generation Core™ i (Gladden) with Cave Creek PCH
- SRIO on ports 4-7 and 8-11 (AMC.4)
- GbE to port 0 and 1 (AMC.2)
- SATA to port 2 and 3 (AMC.3)
- Dual GbE to the front panel
- Up to 16GB of DDR-III memory with ECC
- · Option for up to 32GBytes of Flash
- Serial over LAN
- IPMI 2.0 compliant
- · RoHS compliant

The AMC722 is a Processor AMC (PrAMC) in a single-width, mid-height AdvancedMC (AMC) form factor based on the Intel $^{\mathbb{R}}$ next generation Core $^{\text{TM}}$ i Processor (Gladden) with Cave Creek PCH. The module follows the AMC.4, AMC.2 and the AMC.3 specifications.

The module provides SRIO x4 on ports 4-11 per AMC.4, dual GbE on ports 0 and 1 per AMC.2, and SATA on ports 2 and 3 per AMC.3. It also provides dual GbE to the front.

The SRIO is V2.1 which supports 1.25, 2.5, 3.125 and 5Gbaud.

The AMC722 has option for up to 16 GB of DDR-III memory with ECC. Further the AMC722 allows for up to 32 GB of FLASH.

The AMC722 has serial over LAN with hardware Random Number Generator (RNG) as seed generator for authentication.

The BIOS allows booting from on board FLASH, off board SATA, PXE boot as well as USB.

VadaTech can modify this product to meet special customer requirements without NRE (minimum order placement is required).



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SPECIFICATIONS

Architecture		
Physical	Dimensions	Single-Width, Mid-Height (Full-Height options)
		Width: 2.89 in. (73.5 mm)
		Depth: 7.11 in. (180.6 mm)
Product Type	AMC Processor	Intel [®] Next Generation Core [™] i with up to four core at 2.0GHz and 8MMB LLC
Standards		
AMC	Туре	AMC.1, AMC.2 and/or AMC.3
Module Management	IPMI	IPMI Version 2.0
SRIO	Lanes	Dual x4 SRIO V2.1 1.25, 2.5, 3.125 and 5Gbaud support
Configuration		
Power	AMC722	18 to 55 Watt (CPU dependent)
Environmental	Temperature	Operating Temperature: 0° to 55° C (Air flow >600 LFM for mid-height)
		Storage Temperature: -40° to +90° C
	Vibration	Operating 9.8 m/s2 (1.0G), 5-500Hz
	Shock	Operating 325G/2ms, 160G/1ms
	Relative Humidity	5 to 95 percent, non-condensing
Front Panel		IPMI Management Control
	LEDs	Activity and User defined
		Dual GbE via RJ-45
	1/0	Dual USB via micro USB
		Dual RS-232 via micro USB
	Mechanical	Hot Swap Ejector Handle
Software Support	Operating Systems	Linux, VxWorks and Windows
Other		
MTBF	Per MIL-217F Handbook > TBD MTTF Hrs.	
Certifications	Designed to meet FCC, CE and UL certifications where applicable	
Standards	VadaTech is certified to both the IS09001:2000 and AS9100B:2004 standards	
Compliance	RoHS and NEBS	
Warranty	Two (2) years	
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Email: info@vadatech.com • www.vadatech.com

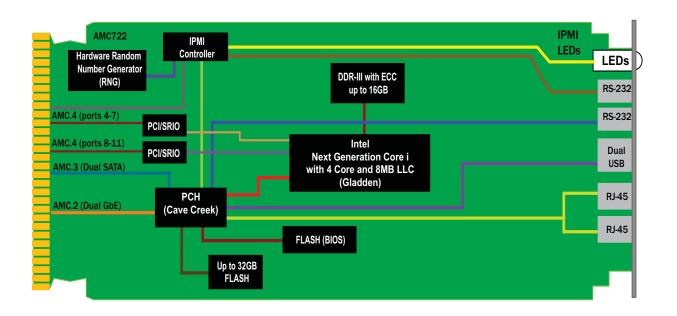
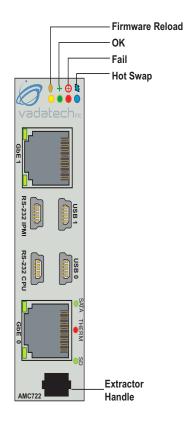


FIGURE 1. AMC722 Functional Block Diagram

FIGURE 2. AMC722 Front Panel



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ORDERING OPTIONS

AMC722 - ABC - D00 - OHJ

A = CPU Core, Speed, Cache

1 = 4C, 2GHz, 8MB LLC (Xeon E3 1125)* 2 = 4C, 1GHz, 6MB LLC (Xeon E3 1105) 3 = 2C, 2GHz, 3MB LLC (Core i3-2115)

4 = Reserved

5 = 2C, 1.5GHz, 3MB LLC (Pentium B915) 6 = 1C, 1.3GHz, 1.5MB LLC (Celeron 725)

B = DDR-III ECC memory

0 = 4GByte

1 = 8GByte

2 = 16G Byte

C = Front Panel*

1 = Reserved

2 = Mid-Height 3 = Full-Height

D = FLASH

0 = None 1 = Reserved 2 = 16GB 3 = 32GB

H = Operating Temp

0 = Commercial Temp 1 = Industrial Temp

J = Conformal Coating

0 = None

1 = Humiseal 1A33 Polyurethane 2 = Humiseal 1B31 Acrylic



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^{*}VadaTech recommends the full-height option for this ordering option so the larger heat sink would accommodate the heat dissipation